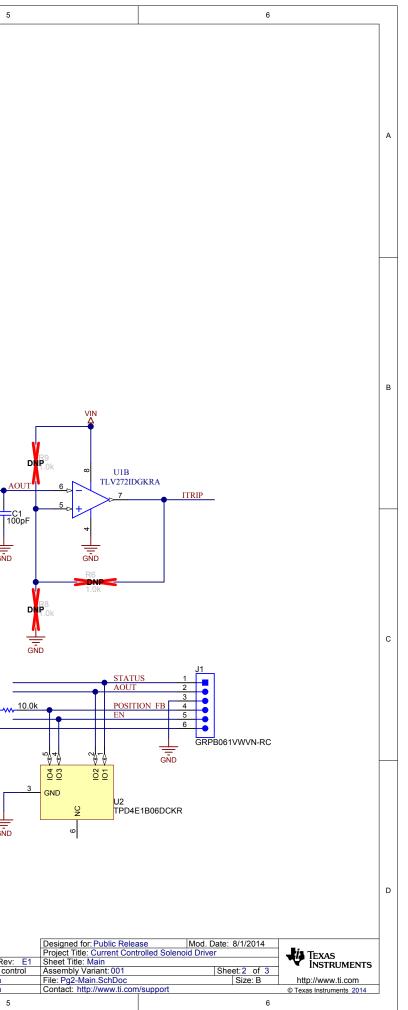
A	A	C3 1UF GND R15 R15 R16	COIL+ D7 MURS160-13-F COIL-	
В	EN R25 10.0k R28 ₹10.0k	$\begin{array}{c} 150k \\ D2 \\ \hline \\ R14 \\ \hline \\ GND \\ \hline \\ \\ GND \\ \hline \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ $	VIN R26 1.0k R27 R24 10 1.0k R27 C7 100pF DPP23 1.00k AOD2N60 DPPC6 0.1µF R22 0.82 R22 0.82 R22 1.0k R22 0.82 R22 1.0k	$R5$ $25k$ $VIN$ $C2$ $0.1\mu F$ $R4$ $AOU'$ $1.0k$ $UIA$ $TLV272IDGKRA$ $UI1$
с	D1 MBR0520LT1G POSITION FB R17 10.0k Q1 TR-BC850 N TR-BC850	Q2 DCJTR-BC850	<u> </u>	R11 GND GND GND GND GND GND GND GND GND GND
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L	abel Table
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ4 Label Assembly Note This Assembly Note is for PCB labels only

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ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2 Assembly Note These assemblies must be clean and free from flux and all contaminants. Us

ZZ3 Assembly Note These assemblies must comply with workmanship standards IPC-A-610 Class

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Designed for: Public Release Mod. Date: Project Title: Current Controlled Solenoid Driver	
Number: TIDA-00284 Rev: E1 Sheet Title:	Texas Instruments
Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not SVN Rev: Not in version control Assembly Variant: 001	t:3 of 3
warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. Texas Instruments and/or its Drawn By: File: Pg3 Hardware ANSI-B.SchDoc	Size: B http://www.ti.com
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